ALLIANCE
MEMORY

FULL MATERIAL DECLARATION

Part Number :	**AS7C1026B-xxTxN & AS7C31026B-xxTxN**		
Package :	**TSOP2-44 pin**	**Approved by**	quality@alliancememory.com
Part Weight :	**468.200** **UOM :** **mg**		Dated:05JUNE2020

No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element Wt $^{(A)}$ (%)	Element Wt (mg)	Wt % Of Total Unit Wt	ppm
1	**Leadframe**	A42	**93.1670**	Silicon(Si)	7440-21-3	0.24	0.224	0.048	478
	FUSHENG			Carbon(C)	7440-44-0	0.05	0.047	0.010	99
				Nickel(Ni)	7440-02-0	40.53	37.761	8.065	80651
				Magnesium(Mg)	7439-95-4	0.68	0.634	0.135	1353
				Iron(Fe)	7439-89-6	55.00	51.242	10.944	109444
				Silver(Ag)	7440-22-4	3.50	3.261	0.696	6965
2	**Die attach material**	4900	**2.7810**	Acrylic resin	Trade secret	7.00	0.195	0.042	416
	Hitachi Epoxy			Polybutadiene derivativee	Trade secret	5.50	0.153	0.033	327
				Butadiene Copoymer	Trade secret	1.00	0.028	0.006	59
				Acrylate	Trade secret	5.50	0.153	0.033	327
				Epoxy resin	Trade secret	2.50	0.070	0.015	148
				Peroxide	Trade secret	0.50	0.014	0.003	30
				Additive	Trade secret	1.00	0.028	0.006	59
				Silver	Trade secret	77.00	2.141	0.457	4574
3	**Gold Wire**	Gold	**0.3740**	Au	7440-57-5	99.99	0.374	0.080	799
	Tanaka			Others		0.01	0.000	0.000	
4	**Tin Plate**	Pure Tin	**8.2420**	Sn	7440-31-5	99.99	8.241	1.760	17602
	Yunnan			others		0.01	0.001	0.000	2
5	**Mold Compound**	CEL-9200HF	**343.9550**	Epoxy resin Proprietary	Trade secret	6.50	22.357	4.775	47751
	Hitachi9200			Carbon Black	1333-86-4	0.20	0.688	0.147	1469
				catalyst	Trade secret	0.50	1.720	0.367	3673
				Silica,amorphous	Trade secret	88.80	305.432	65.235	652354
				Phenolic Resin	9003-35-4	4.00	13.758	2.939	29385
6	Die	Silicon Chip	**19.6810**	Si	-	100	19.681	4.2035	42035
	Total unit weight =		**468.200**						

Note:

(A) Element Wt Composition is derived from MSDS and/or material C of C from Vendors

(B) Wt of silver spotted on leadframe is estimated.

(C) Component Weight based on assembly of generic parts.